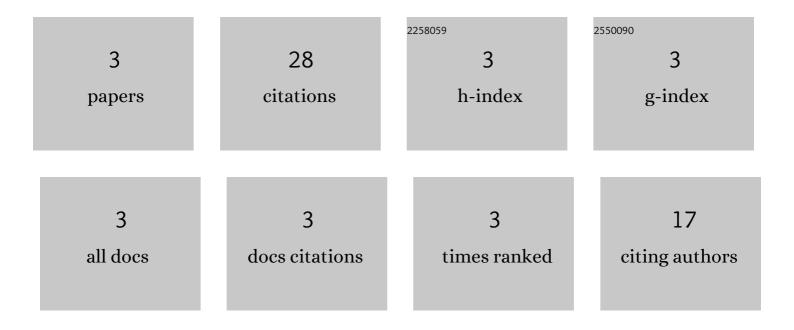
## Xu Fang

## List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/2427717/publications.pdf Version: 2024-02-01



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| # | Article  | IF  | CITATIONS |
|---|--|-----|-----------|
| 1 | A Post-Bond TSV Test Method Based on RGC Parameters Measurement. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2020, 39, 506-519. | 2.7 | 12        |
| 2 | TSV Prebond Test Method Based on Switched Capacitors. IEEE Transactions on Very Large Scale<br>Integration (VLSI) Systems, 2019, 27, 205-218.                      | 3.1 | 7         |
| 3 | TSV-Defect Modeling, Detection and Diagnosis Based on 3-D Full Wave Simulation and Parametric<br>Measurement. IEEE Access, 2018, 6, 72415-72426.                   | 4.2 | 9         |